

32GB Computer memory DDR3 for ORACLE SUN Fire X6270 M3 RDIMM



93,78 EUR

plus VAT

111,60 EUR

incl. VAT

en stock

<https://www.phs-memory.fr>

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Your benefits

- ✓ verified quality memory
- ✓ 5 years warranty
Warranty details see last page
- ✓ 100% compatible
- ✓ free support on our hotline
- ✓ fast delivery

PHS-memory® - computer memory with 100% quality

- many years of IT competence
- Free support for optimal configuration and product selection
- High availability through professional warehouse management
- Fast delivery in throughout Europe
- Short response times and professional order processing due to full digitalization throughout the entire process with complete traceability
- Incoming goods inspection include checks of the DRAMs, PCBs and the programmed SPDs in order to exclude possible errors (Controlled BOM).
- PHS-memory® brand memories guarantee 100% compatibility to the specified system.
- PHS-memory® memories can be used together with existing memories in the device - depends on to the configuration rules of the system.
- The "fallback option" in the SPD of PHS-memory® allows DRAMs with higher clock rates to be operated together with older memory modules with lower clock rates within the system.
- Products with unique serial number for service and warranty
- Pre-sales and after-sales support by technically trained personnel

Memory Specification



Memory size	32GB
Memory technology	DDR3
ECC support	yes
JEDEC Norm	PC3L-12800R
DRAM Organization	2Gx4
Rank	4Rx4 (4DRx4 DDP)
Type	RDIMM (ECC Registered)
Number of pins	240 Pin DIMM
Memory data transfer rate	1600MHz @ CL11
Voltage	1,35 Volt
Speciality	DDP
Board dimensions	133,35 x 30 (LxB mm)
Operating temperature	0° C - 85° C
Storage temperature	-40° C - +95° C
RoHS compliant	yes
SKU	SP466091
EAN	4067488296048

overRAMing - maximize your RAM



overRAMing Project

Most systems - including the ORACLE SUN Fire X6270 M3 - can be upgraded with more memory than originally specified by the device manufacturer.

Therefore, our memory specialists continuously analyze new memory solutions in selected systems. Due to improved manufacturing technologies, new memories with higher performance and capacity will be tested for stability and functionality.

Then the new memory solutions are released for the respective systems. Use the benefits of larger computer memory capacity with the PHS-memory® overRAMing memory solutions.

<https://www.phs-memory.fr/-BOR>

Note: The module specified in this datasheet is one of several possible configurations available under this part number.
Some details may differ from the specifications described here and the illustration, but have no negative influence on the functionality.

System Specifications

The memory is 100% compatible with this system:

System manufacturer	ORACLE
Device type	Server
Device family	SUN Server
Device series	Fire X Serie
Device name	SUN Fire X6270 M3
Maximum memory*	512GB / 256GB according to manufacturer
Number of memory sockets	16

* The specifications for the maximum memory upgrade may differ from those of the manufacturer ORACLE. Often the information given in the manual for the maximum memory upgrade is not up to date. New memory technologies, bios updates or newer software versions often allow the use of memory modules with a higher capacity than specified by the manufacturer with the same performance and stability.

Memory modules with our overRAMing-symbol are approved by us for maximum memory expansion.

Information on memory allocation

Which memory configuration is possible?

Our memory team will be happy to help you choose the right memory and configure your server.

Principles of memory assembly

- Each CPU has 4 memory channels with 3 memory slots each
- memorysteckplätze for die kein Prozessor vorhanden ist dürfen nicht bestückt werden

Memory configuration for good system performance

- Verteilen Sie die memory gleichmäßig auf die memorysteckplätze and gleichmäßig auf die CPUs
- Wenn mehr als eine CPU vorhanden sind, sollten die memory pro CPU identisch (gespiegelt zur anderen CPU) bestückt werden.

Information on memory installation

- Turn off the system
- Remove the plug of the power supply unit (if connected)
- Remove the battery, according to the user manual of the system
- Always ground yourself before touching electronic components
- Protect the memory module from static voltages:
 - Do not touch the gold pins of the memory module
 - Only touch the sides of the memory module
 - Use a grounding strap and/or ESD glove if possible

General installation instructions are supplied by E-Mail.

Further memory options for ORACLE SUN Fire X6270 M3

Size	SKU	Technology	Type	Number of pins	Brand	Reference no.
8GB	SP236765	DDR3	RDIMM (ECC Registered)	240 Pin DIMM	PHS-memory®	7102797
16GB	SP236766	DDR3	RDIMM (ECC Registered)	240 Pin DIMM	PHS-memory®	7102800
32GB	SP466091	DDR3	RDIMM (ECC Registered)	240 Pin DIMM	PHS-memory®	

PHS-memory® warranty

Every PHS-memory® is equipped with a 5-years-warranty of perfect operation. If the RAM module is defective or fails within 5 years of purchase when used properly, you will receive an appropriate RAM module free of charge. If a suitable memory module is no longer available, we will refund the purchase price.

For more information on warranty and service please visit <https://www.phs-memory.fr/-W5Y>



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All information without guarantee. Technical changes and errors excepted. You can find current price information in our online shop at <https://www.phs-memory.fr>